



Title of Change:	Optical Device Chip Scale Package (ODCSP) site change from Gunma, Japan to Niigata, Japan and Dicing site change from Shenzhen, China to Tarlac, Philippines		
Proposed first ship date:	19 September 2016		
Contact information:	Contact your local ON Semiconductor Sales Office or <Hiroshi.Kojima@onsemi.com>		
Samples:	Contact your local ON Semiconductor Sales Office.		
Type of notification:	<p>This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.</p> <p>The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.</p>		
Change Part Identification:	Product lots will be identified through a date code marked on the parts.		
Change category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input checked="" type="checkbox"/> Test Change <input type="checkbox"/> Other _____		
Change Sub-Category(s): <div style="display: flex; flex-wrap: wrap;"> <div style="width: 33%;"><input checked="" type="checkbox"/> Manufacturing Site Change/Addition</div> <div style="width: 33%;"><input type="checkbox"/> Material Change</div> <div style="width: 33%;"><input type="checkbox"/> Datasheet/Product Doc change</div> <div style="width: 33%;"><input type="checkbox"/> Manufacturing Process Change</div> <div style="width: 33%;"><input type="checkbox"/> Product specific change</div> <div style="width: 33%;"><input type="checkbox"/> Shipping/Packaging/Marking</div> <div style="width: 33%;"><input type="checkbox"/> Other: _____</div> </div>			
Sites Affected: <div style="display: flex; flex-wrap: wrap;"> <div style="width: 33%;"> <input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable </div> <div style="width: 33%;"> <input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Niigata, Japan ON Gunma, Japan ON Tarlac, Philippines ON Shenzhen, China </div> <div style="width: 33%;"> <input type="checkbox"/> External Foundry/Subcon site(s) </div> </div>			
Description and Purpose: <p>This is an Initial Notification to announce the continuous supply of products and increase supply capacity to support increased demand. The Optical Device Chip Scale Package (ODCSP) location will move from Gunma, Japan to Niigata, Japan and dicing site location will move from Shenzhen, China to Tarlac city, Philippines. All equipment and most personnel will be transferred from Gunma to Niigata site and most equipment will be transferred from Shenzhen to Tarlac site. The Niigata and Tarlac site are ISO/TS16949 certified.</p>			
Qualification Plan: QV DEVICE NAME : LV0318XP PACKAGE: ODCSP16			
Test	Specification	Condition	Interval
HTOL	EIAJ ED-4701/100	Ta=70°C, Vcc = operating max	1008 hrs
HTSL	EIAJ ED-4701/200	Ta= 100°C	1008 hrs
TC	EIAJ ED-4701/100	Ta= -40°C to +100°C	100 cyc
THB	EIAJ ED-4701/100	60°C, 90% RH, Vcc = recommended	1008 hrs



IQV DEVICE NAME : LV0222CS

PACKAGE: ODCSP8

Test	Specification	Condition	Interval
HTOL	EIAJ ED-4701/100	Ta=60°C, Vcc = operating max	1008 hrs
HTSL	EIAJ ED-4701/200	Ta= 100°C	1008 hrs
TC	EIAJ ED-4701/100	Ta= -40°C to +100°C	100 cyc
THB	EIAJ ED-4701/100	60°C, 90% RH, Vcc = recommended	1008 hrs

Estimated date for qualification completion: 17 June 2016

List of Affected Standard Parts:

Part Number	Qualification Vehicle
LV0104CS-TLM-H	LV0318XA-NH
LA0151CS-TLM-E	LV0318XA-NH
LV0111CF-TLM-H	LV0318XA-NH
LV0222CS-TLM-H	LV0222CS-TLM-H
LV0229XA-NH	LV0318XA-NH
LV0221CS-TLM-H	LV0318XA-NH